



Device Material Content

5555 NE Moore Ct. Hillsboro OR
97124 custreq@latticesemi.com

Package: 32 QFNS
Total Device Weight(g): 0.0699

Package Code:

SG32

Products

MX02-256HC

Assembly : ASEK
Size(mm): 5X5X0.4
Lead pitch(mm) : 0.5

MSL : 3
Reflow max (°C) 260

May, 2024

	% of Material / Total Pkg. Wt.	Material Weight (mg)	% of Substance/ Total Pkg. Wt.	Substance Weight (mg)	Material Substances	CAS #	Material % of Subst.	Notes / Assumptions:
Die	5.579%	3.900	5.579%	3.900	Silicon	7440-21-3	100.000%	
Mold Compound	55.079%	38.500	1.619%	1.132	2,2'-(3,3',5,5'-Tetramethyl-4	85954-11-6	2.940%	EME-G631-H
			1.619%	1.132	Epoxy Resin	Trade Secret	2.940%	
			4.048%	2.829	Phenol Resin	Trade Secret	7.349%	
			37.781%	26.409	Silica(Amorphous) A	60676-86-0	68.594%	
			8.096%	5.659	Silica(Amorphous) B	7631-86-9	14.699%	
			1.619%	1.132	Metal Hydroxide	Trade Secret	2.940%	
			0.297%	0.207	Carbon Black	1333-86-4	0.539%	
Leadframe	35.765%	25.000	1.050%	0.734	Nickel	7440-02-0	2.937%	C7025
			0.232%	0.163	Silicon	7440-21-3	0.650%	Silver Plating Leadframe
			0.056%	0.039	Magnesium	7439-95-4	0.157%	
			2.253%	1.575	Silver	7440-22-4	6.300%	
			32.173%	22.489	Copper	7440-50-8	89.957%	
Die Attach Epoxy	1.574%	1.100	0.115%	0.080	2-Phenoxyethyl Acrylate	48145-04-6	7.317%	EN-4900F
			0.023%	0.016	Substitutedalkoxyalkyl trim	2530-83-8	1.463%	
			1.151%	0.805	Silver	7440-22-4	73.171%	
			0.154%	0.107	Polybutadiene epoxidized	Trade secret	9.756%	
			0.008%	0.005	Butadiene copolymer	Trade secret	0.488%	
			0.115%	0.080	Bisphenol F diacrylate	Trade secret	7.317%	
			0.008%	0.005	Peroxy Ketals	Trade secret	0.488%	
Bonding Wire	1.431%	1.000	1.422%	0.994	Gold	7440-57-5	99.42%	PdAu
			0.008%	0.006	Palladium	7440-05-3	0.58%	
External Plating	0.572%	0.400	0.572%	0.400	Tin (Sn)	7440-31-5	99.995%	Matte Sn
			0.00003%	0.000	Impurities	-	0.005%	
			100.000%	69.900	100.000%	69.900		

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible. Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

www.latticesemi.com



PCN#09A-19
Rev. F